



PRODUCT DATASHEET

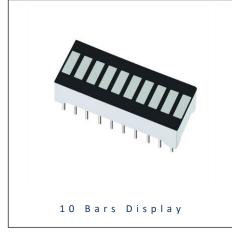


- Red (640nm)









NOR09D58BS

APPLICATIONS:

- LED Display •
- Indicator
- **Counting System**

FEATURES:

- Package: Black Surface Throughhole 10 Bars LED Graphic Display
- Forward Current: 20mA*
- Forward Voltage (typ.): 1.9V* .
- Luminous Intensity (typ.): 10mcd @20mA* •
- . Colour: Red
- Dominant Wavelength (typ.): 640nm •
 - Materials:

•

- Die: AlInGaP _
- Resin: Epoxy (White Diffused) _
- Operating Temperature: -40~+85°C
- Storage Temperature: -40~+100°C
- **Grouping Parameters:** •
 - _ Forward voltage
 - Luminous intensity
 - Dominant wavelength
- Soldering Methods: Soldering Heat (DIP)
- Packing: carton

* per single bar



CHARACTERISTICS:

Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Forward Current	lf	30	Ma
Peak Forward Current Duty 1/10@1KHz	IFP	100	Ma
Reverse Current @5V	IR	10	μΑ
Power Dissipation	PD	85	mW
Electrostatic Discharge	ESD	2000	V
Operating Temperature	Topr	-40~+85	°C
Storage Temperature	T _{STG}	-40~+100	°C

Electrical & Optical Characteristics (Ta=25°C)

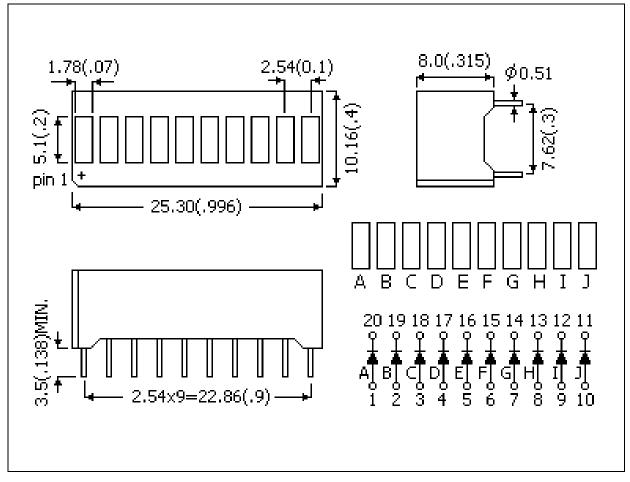
Darameter	Symbol	Values			Upit	Test
Parameter		Min.	Тур.	Max.	Unit	Condition
Forward Voltage	VF	1.8	1.9	2.4	V	I⊧=20mA
Luminous Intensity	lv	8	10	15	mcd	I⊧=20mA
Dominant Wavelength	λ_{D}	635	640	645	nm	I⊧=20mA
Peak Wavelength	λ_{P}		650		nm	I⊧=20mA
Spectral Half Bandwidth	Δλ		20		nm	I⊧=20mA

1. Luminous intensity (I_v) ±15%, Forward Voltage (V_F) ±0.1V, Viewing angle(2 $\theta_{1/2}$) ±5%



OUTLINE DIMENSION:

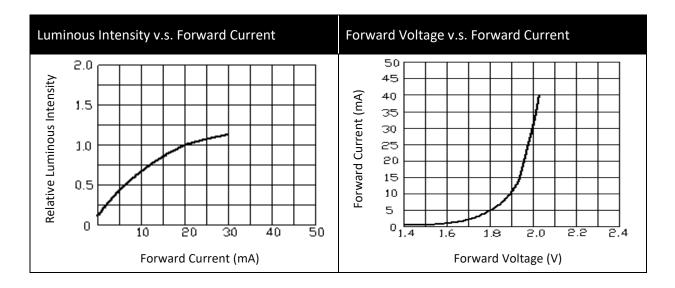


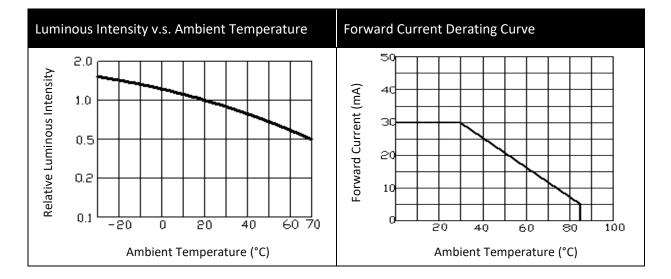


- 1. All dimensions are in millimetre (mm).
- 2. Tolerance ±0.2mm, unless otherwise noted.



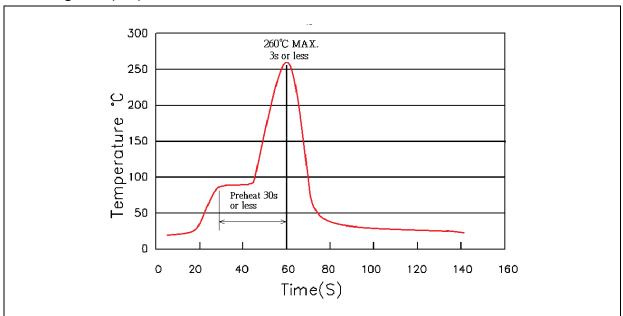
ELECTRO-OPTICAL CHARACTERISTICS:







RECOMMENDED SOLDERING PROFILE:



Soldering Heat (DIP) Solder:

Note:

- 1. Maximum reflow soldering: 1 time.
- 2. Before, during, and after soldering, should not apply stress on the components and PCB board.

PRECAUTIONS OF USE:



Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a year. Otherwise, they should be kept in a damp-proof box with descanting agent <10% R.H. and apply baking before use.

Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

• 60±3°C x 24hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.



REVISION RECORD:

Version	Date	Summary of Revision
A1.0	06/06/2014	Datasheet set-up.
A1.1	18/01/2023	Update intensity level.
A1.2	18/03/2023	Update product photo.
A1.3	08/12/2023	Update storage condition.